Preferred Device

General Purpose Transistor

PNP Silicon

Features

• Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	-40	Vdc
Collector - Base Voltage	V _{CBO}	-40	Vdc
Emitter - Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current - Continuous	Ic	-200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1) $T_A = 25^{\circ}C$	P _D	1.5 12	W mW/°C
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W
Thermal Resistance Junction-to-Lead #4	$R_{\theta JA}$	35	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

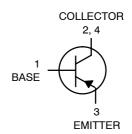
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 with 1 oz and 713 mm² of copper area.

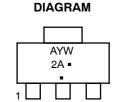


ON Semiconductor®

http://onsemi.com







MARKING

2A = Specific Device Code = Assembly Location Α

Υ = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
PZT3906T1	SOT-223	1000 / Tape & Reel
PZT3906T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel

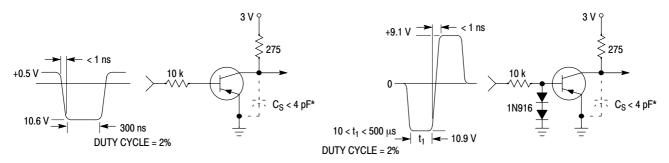
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Charac	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS (Note 2)		- 1		•	•
Collector – Emitter Breakdown Voltage (Note $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	2)	V _{(BR)CEO}	-40	_	Vdc
Collector – Base Breakdown Voltage ($I_C = -10 \mu Adc, I_E = 0$)	V _{(BR)CBO}	-40	_		
Emitter – Base Breakdown Voltage ($I_C = -10 \mu Adc, I_C = 0$)		V _{(BR)EBO}	-5.0	_	
Base Cutoff Current (V _{CE} = -30 Vdc, V _{EB} = -3.0 Vdc)	I _{BL}	-	-50	nAdc	
Collector Cutoff Current (V _{CE} = -30 Vdc, V _{EB} = -3.0 Vdc)	I _{CEX}	-	-50		
ON CHARACTERISTICS (Note 2)					•
$\begin{array}{l} \text{DC Current Gain} \\ (I_C = -0.1 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ (I_C = -1.0 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ (I_C = -10 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ (I_C = -50 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ (I_C = -100 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \end{array}$		H _{FE}	60 80 100 60 30	- 300 - -	-
Collector – Emitter Saturation Voltage ($I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ($I_C = -50$ mAdc, $I_B = -5.0$ mAdc)			- -	-0.25 -0.4	Vdc
Base – Emitter Saturation Voltage ($I_C = -10 \text{ mAdc}$, $I_B = -1.0 \text{ mAdc}$) ($I_C = -50 \text{ mAdc}$, $I_B = -5.0 \text{ mAdc}$)	V _{BE(sat)}	-0.65 -	-0.85 -0.95		
SMALL-SIGNAL CHARACTERISTICS		1			
Current – Gain – Bandwidth Product ($I_C = -10$ mAdc, $V_{CE} = -20$ Vdc, $f = 100$ MHz)			250	-	MHz
Output Capacitance (V _{CB} = -5.0 Vdc, I _E = 0, f = 1.0 MHz)			1	4.5	pF
Input Capacitance ($V_{EB} = -0.5 \text{ Vdc}$, $I_{C} = 0$, $f = 1.0 \text{ MHz}$)		C _{ibo}	ı	10	
Input Impedance (I _C = -1.0 mAdc, V _{CE} = -10 Vdc, f = 1.0 kH	Hz)	h _{ie}	2.0	12	kΩ
Voltage Feedback Ratio ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$	Hz)	h _{re}	0.1	10	X 10 ⁻⁴
Small – Signal Current Gain ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)			100	400	-
Output Admittance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)			3.0	60	μmhos
Noise Figure (I _C = $-100 \mu Adc$, V _{CE} = $-5.0 Vdc$, R _S = $1.0 \mu Adc$	NF	ı	4.0	dB	
SWITCHING CHARACTERISTICS					
Delay Time	$(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc},$	t _d	-	35	
Rise Time	$I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	t _r	_	35	ne
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc},$	t _s	_	225	ns
Fall Time	$I_{B1} = I_{B2} = -1.0 \text{ mAdc}$	t _f	-	75	

^{2.} Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.



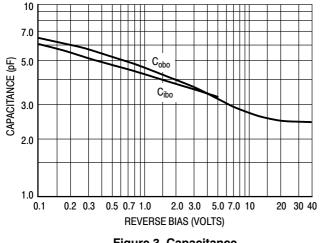
* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS

T_J = 25°C
T_J = 125°C



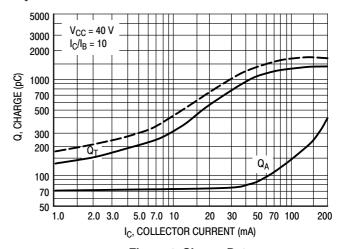


Figure 3. Capacitance 500 $I_{\rm C}/I_{\rm B}=10$ 300 200 100 70 TIME (ns) $t_r @ V_{CC} = 3.0 \$ 50 30 20 10 $t_{d} @ V_{OB} = 0 V$ 2.0 3.0 5.0 7.0 10 20 70 100 1.0 200 IC, COLLECTOR CURRENT (mA)

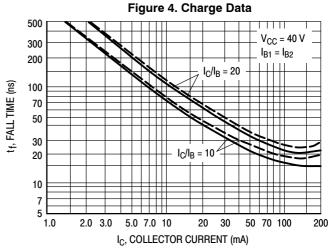


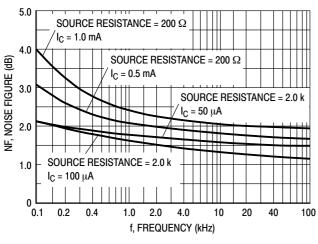
Figure 5. Turn - On Time

Figure 6. Fall Time

TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$

NF, NOISE FIGURE (dB)



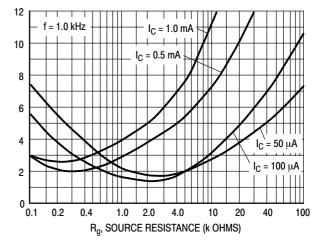


Figure 7.

Figure 8.

h PARAMETERS

 $(V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$

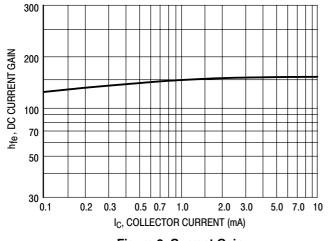
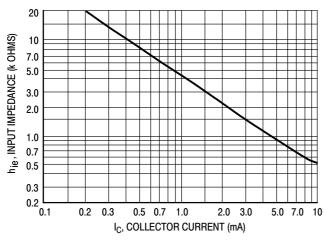


Figure 9. Current Gain

Figure 10. Output Admittance



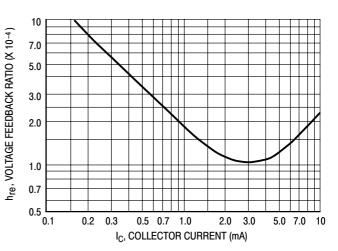


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

TYPICAL STATIC CHARACTERISTICS

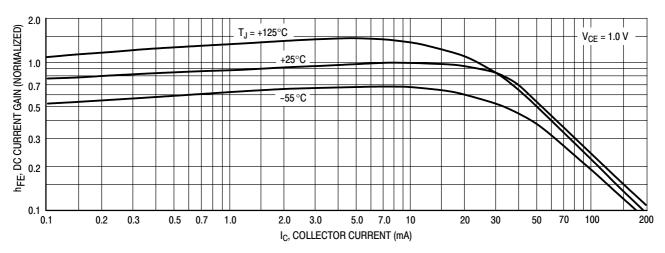


Figure 13. DC Current Gain

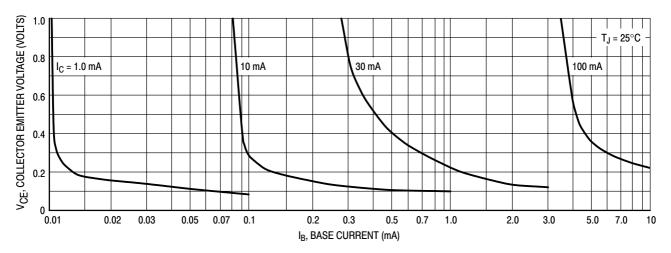


Figure 14. Collector Saturation Region

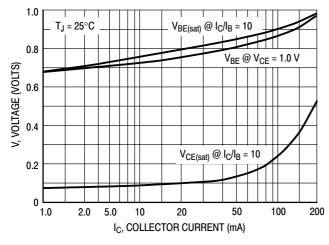


Figure 15. "ON" Voltages

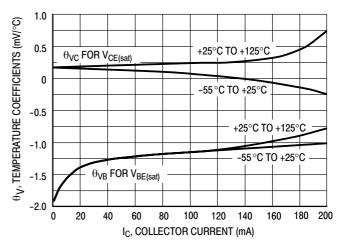
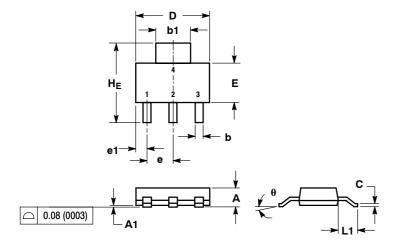


Figure 16. Temperature Coefficients

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE L



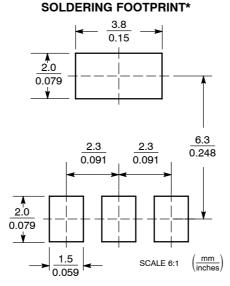
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
 - Y14.5M, 1982
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	-	10°

STYLE 1:

- PIN 1. BASE
 - 2. COLLECTOR
 - 3. EMITTER



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and was are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.